

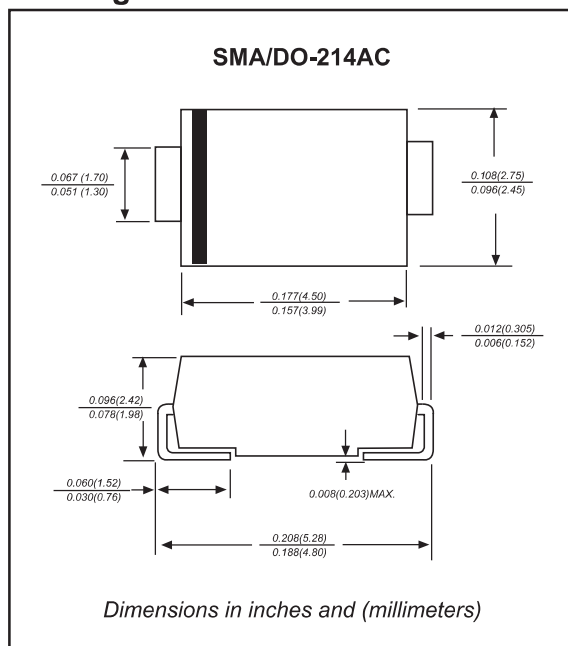
Features

- Ideal for surface mounted application
- Low profile surface mounted application in order to optimize board space
- Built-in strain relief design
- Ultra fast recovery time for high efficient
- Glass passivated chip junction
- Lead-free parts meet RoHS requirements
- Compliant to Halogen-free

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SMA(DO-214AC)
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

Package outline



Maximum ratings (AT T_A=25°C unless otherwise noted)

PARAMETER	SYMBOLS	MURA120T3G	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	200	V
Maximum RMS voltage	V _{RMS}	140	V
Maximum continuous reverse voltage	V _R	200	V
Maximum average forward rectified current	I _O	1.0	A
Non-repetitive peak forward surge current 8.3ms single half sine-wave	I _{FSM}	40	A
Typical junction capacitance (Note 1)	C _J	15	pF
Operating junction temperature range	T _J	-55 to +175	°C
Storage temperature range	T _{STG}	-65 to +175	°C

Electrical characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	SYMBOLS	MURA120T3G	UNITS
Maximum instantaneous forward voltage at I _F =1.0A T _J =25°C	V _F	0.875	V
Maximum instantaneous forward voltage at I _F =1.0A T _J =150°C	V _F	0.71	V
Maximum reverse leakage current at rated V _R	I _R	2.0 50	μA
Maximum reverse recovery time, (Note 2)	t _{rr}	25	ns

Thermal characteristics

PARAMETER	SYMBOLS	MURA120T3G	UNITS
Typical thermal resistance junction to ambient , (Note 3)	R _{θJA}	25	°C / W
Typical thermal resistance junction to case , (Note 3)	R _{θJC}	15	°C / W

Notes 1: Measured at 1 MHz and applied reverse voltage of 4.0 VDC
 2: Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A
 3: Mounted on FR-4 PCB Copper, minimum recommended pad layout

Rating and characteristic curves

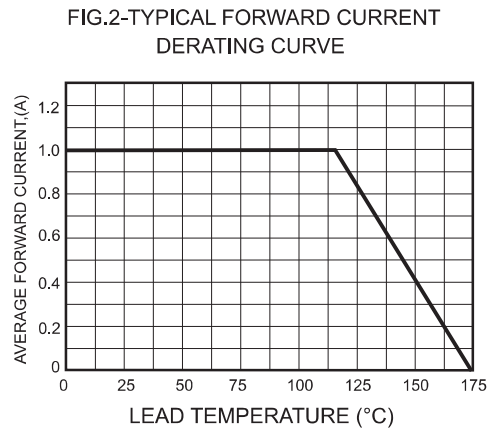
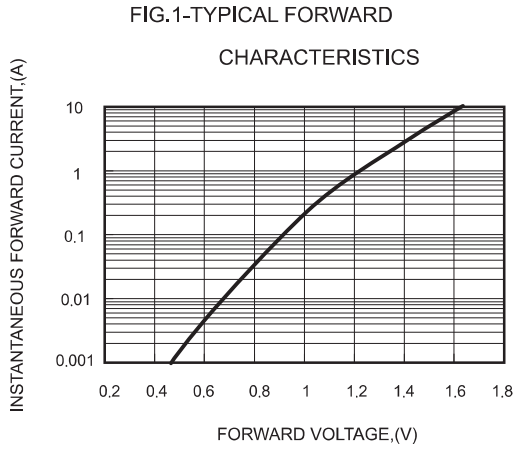
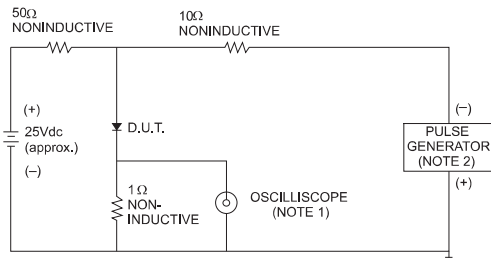


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

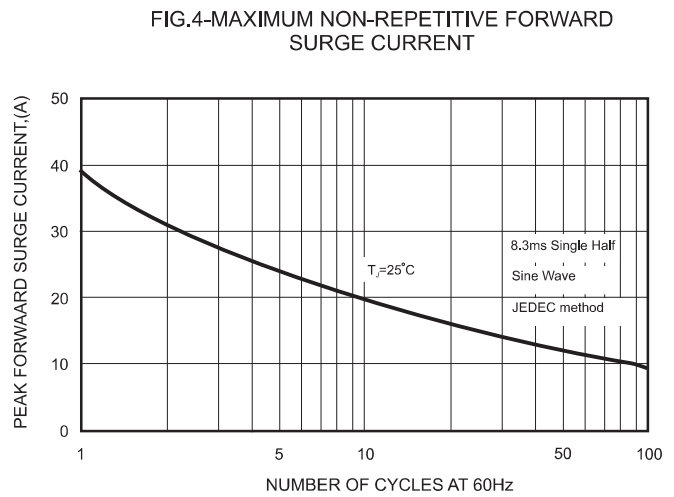
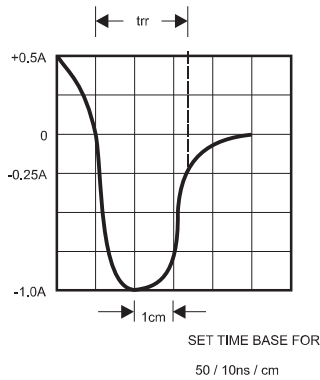
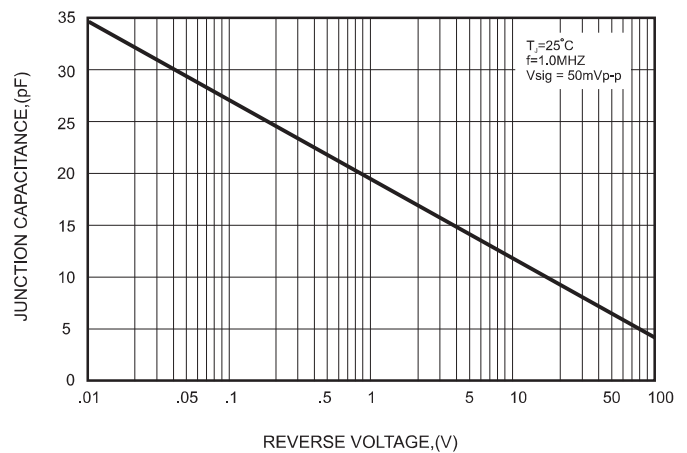




FIG.5-TYPICAL JUNCTION CAPACITANCE



Pinning information

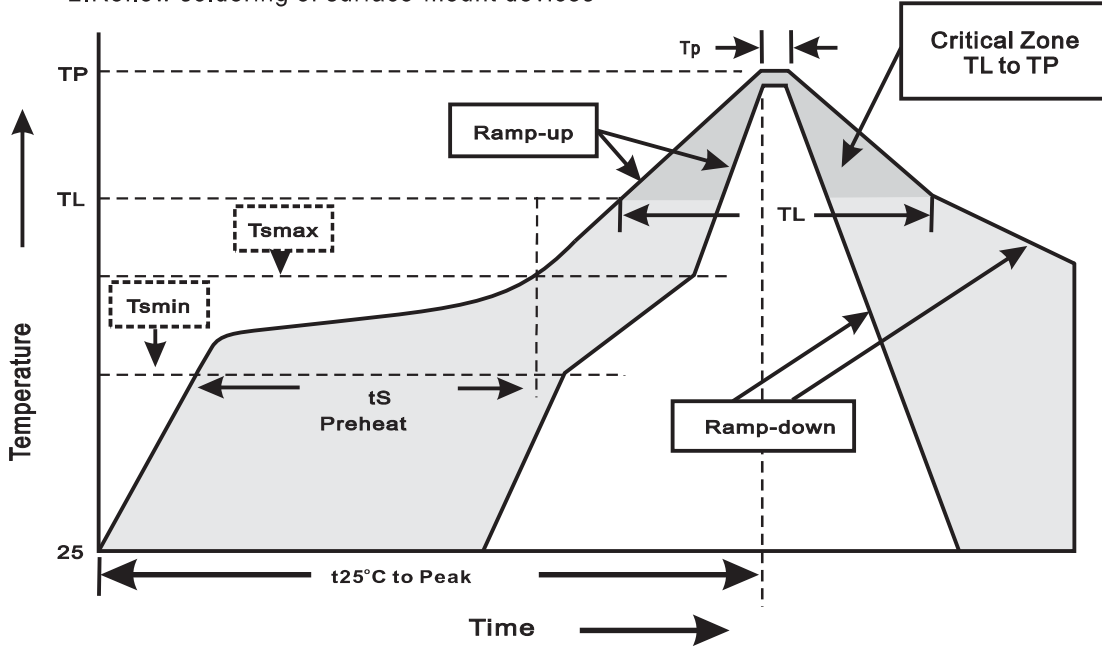
Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
MURA120T3G	U4D

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes